



**AAEON Technology INC.**  
ISO-9001/ISO-14001 Certified  
Industrial Automation PCs

# **SBC-658**

## **Thermal Image Analysis Report**

**Release Date: JUNE.29, 2000**

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**Issue Stamp**

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**QA Manager**

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**QE Manager**

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**Test Engineer**

# Thermal Image Analysis

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**I . Model Name: SBC-658**

**II . Description: FC/Socket 370 Half-size CPU Card with LCD, Ethernet, & SSD**

**III . Date: JUNE. 29, 2000**

**IV. Measure Site: AAEON QE Dept.**

**V . Issued by : Fenglin Dong**

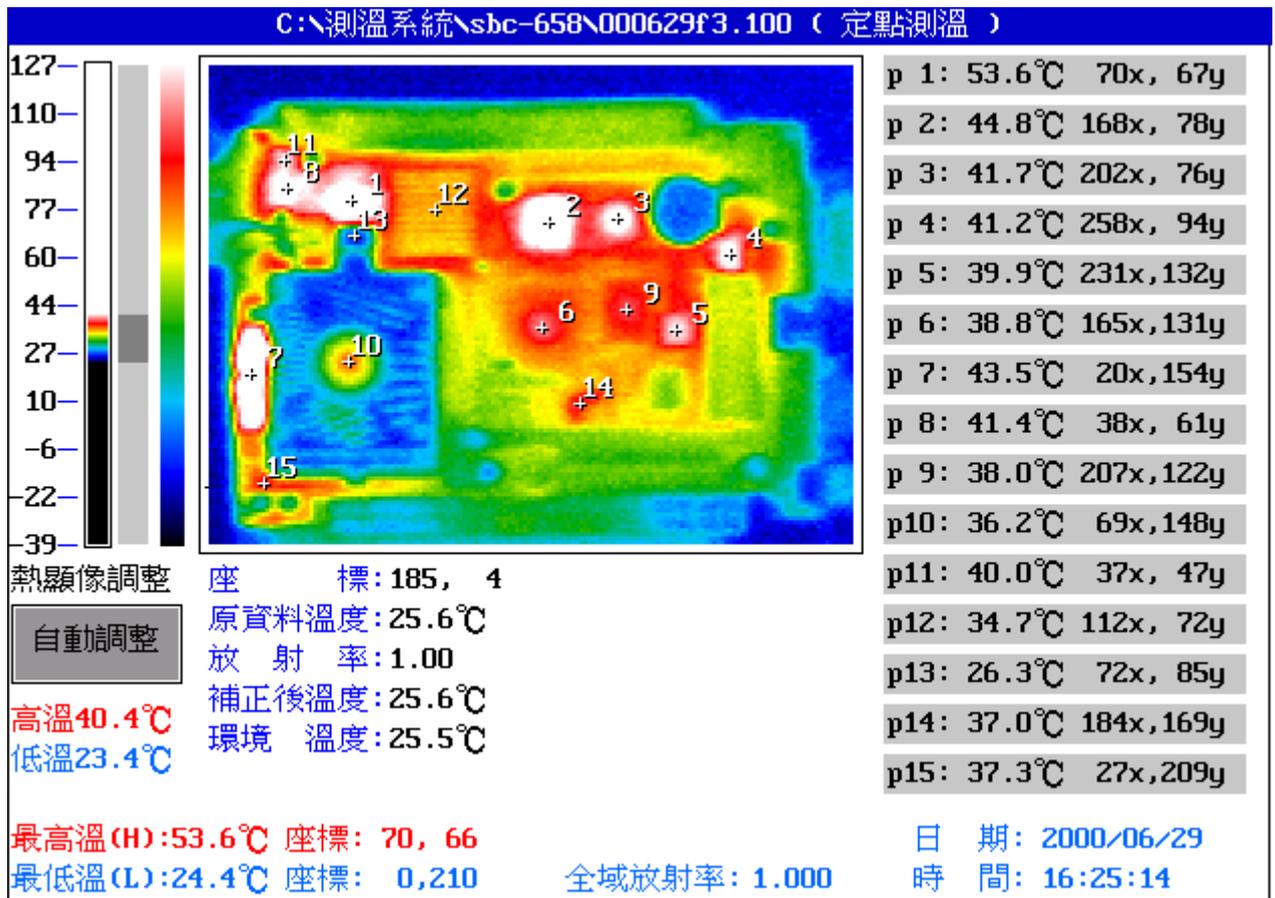
**VI.Equipment: TVS-100 series by NIPPON AVIONICS CO., LTD.**

**VII. Simulation Environment:**

- **Temperature: 25.5 degrees C**
- **CPU: PIII 700**
- **RAM: 128 MB (NEC D4564841G5-A80-9JF)**
- **Hardware: DiskOnChip**
- **Application Software: QAplusfe V5.2**
- **Take Picture Time: Power on 30 minutes after**

## VIII. Prediction Result:

### 1. Component Side:



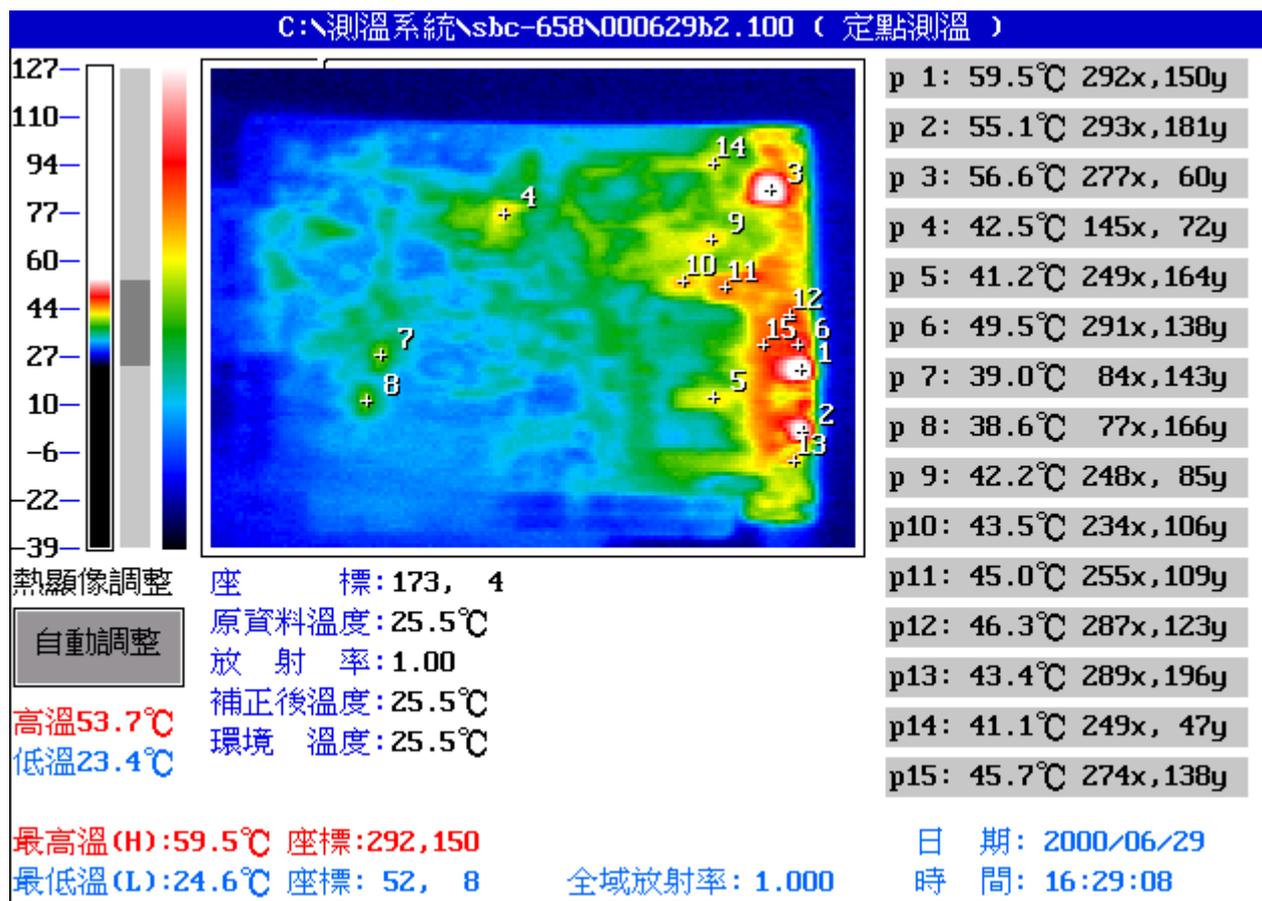
Point	Position	Describe	Ts	Tm	Note
1	U2	ICS, 9248-39	70	53.6	※
2	U4	INTEL, C&TM6900	75	44.8	※
3	U5	INTEL, 82559ER	75	41.7	※
4	U7	LINEAR, LTC485CS8	70	41.2	※
5	U14			39.9	
6	U13			38.8	
7	U1	HARRIS, HIN213CA	75	43.5	※
8	CN6	鴻呈, AT-PH13-SMT-14-2-G	70	41.4	※
9	U11			38.0	
10	CPU1			36.2	
11	CN6			40.0	
12	U3			34.7	
13	---			---	
14	U21			37.0	
15	---			---	

#### 1. Operation Temperature (°C):

Ts = Defined by component specification ; Tm = Measured by QE

2. ※ = Ts - (Tm + 60 - 25)

## 2. Solder Side:



Point	Position	Describe	Ts	Tm	Note
1	Q6	PHILIPS, PHD50N03LT	75	59.5	※ = -19.5
2	Q5	PHILIPS, PHD50N03LT	75	55.1	※ = -15.1
3	Q2	AMS, AMS1083CM	75	56.6	※ = -16.6
4	---			---	
5	C115			41.2	
6	---			---	
7	---			---	
8	---			---	
9	---			---	
10	U27	74F070	70	43.5	※ = -8.5
11	Q3	AMS, AMS1084CM-1.5	70	45.0	※ = -10
12	C108	MCC, 1 μF, 10V, +80/-20%, 0603SMD	75	46.3	※ = -6.3
13	---			---	
14	---			---	
15	---			---	

### 1. Operation Temperature (°C):

Ts = Defined by component specification ; Tm = Measured by QE

2. ※ = Ts - (Tm + 60 - 25)